

**BIRLA INSTITUTE OF TECHNOLOGY, MESRA, RANCHI
(END SEMESTER EXAMINATION)**

**CLASS: IMSC / MSC/ PHD
BRANCH: PHYSICS**

**SEMESTER : X/IV/NA
SESSION : SP/2025**

SUBJECT: PH519: PHYSICS OF THIN FILM

TIME: 3 Hours

FULL MARKS: 50

INSTRUCTIONS:

1. The question paper contains 5 questions each of 10 marks and total 50 marks.
 2. Attempt all questions.
 3. The missing data, if any, may be assumed suitably.
 4. Before attempting the question paper, be sure that you have got the correct question paper.
 5. Tables/Data hand book/Graph paper etc. to be supplied to the candidates in the examination hall.
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Q.1(a) Define pumping speed, throughput and conductance in vacuum systems. Air at room temperature (20°C) is flowing under molecular flow conditions, through a series connection of two tubes having diameters 12 cm and 6 cm, and lengths 10 cm and 14 cm, respectively. What is the overall conductance of this arrangement?	[5]	01
Q.1(b) Explain the pumping mechanism of a diffusion pump with the help of a schematic diagram. What is the importance of the baffle and cold trap in a diffusion pump system?	[5]	01
Q.2(a) State the working principle of the Zero Creep Method for surface energy measurement. How is the condition of “zero creep” related to surface energy in case of amorphous solids?	[5]	02
Q.2(b) Differentiate between steady state and non-steady state diffusion. A plate of iron is exposed to a carburizing (carbon-rich) atmosphere on one side and a decarburizing (carbon-deficient) atmosphere on the other side at 700°C. If a condition of steady state is achieved, calculate the diffusion flux of carbon through the plate if the concentrations of carbon at positions of 5 mm and 10 mm beneath the carburizing surface are 1.2 and 0.8 kg/m ³ , respectively. Assume a diffusion coefficient of 3×10^{-11} m ² /s at this temperature.	[5]	02
Q.3(a) State the different stages involved in thin film formation during physical vapor deposition (PVD). How does adatom mobility influence this process?	[5]	03
Q.3(b) Explain the classical growth modes in thin film formation. What determines the selection of each mode?	[5]	03
Q.4(a) Compare DC and RF sputtering in terms of working principle, applications, and suitability for different types of target materials. A researcher needs to deposit a thin film of SiO ₂ (an insulating material). Which sputtering technique would be most appropriate and why?	[5]	04
Q.4(b) Explain the working principle of Thermal CVD. How is plasma used in PECVD to enhance the deposition process? What are the advantages of PECVD over Thermal CVD?	[5]	04
Q.5(a) Explain the four-point probe method for measuring sheet resistance of thin films. Why is it preferred over the two-point method?	[5]	05
Q.5(b) State the Scherrer formula and explain each term. Under what conditions is this method valid for estimating crystallite size?	[5]	05

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